



US 20240251686A1

(19) **United States**

(12) **Patent Application Publication**
KANG et al.

(10) **Pub. No.: US 2024/0251686 A1**

(43) **Pub. Date: Jul. 25, 2024**

(54) **LINEAR RESISTIVE ELEMENT AND
PREPARATION METHOD**

Publication Classification

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(51) **Int. Cl.**
H10N 70/00 (2006.01)
H10N 70/20 (2006.01)

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(52) **U.S. Cl.**
CPC **H10N 70/823** (2023.02); **H10N 70/011**
(2023.02); **H10N 70/24** (2023.02)

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(57) **ABSTRACT**

(21) Appl. No.: **18/426,367**

(22) Filed: **Jan. 30, 2024**

Related U.S. Application Data

(63) Continuation of application No. PCT/CN2022/
105406, filed on Jul. 13, 2022.

(30) **Foreign Application Priority Data**

Nov. 22, 2021 (CN) 202111386648.3

Disclosed in embodiments of the present application are a linear resistive element and a preparation method therefor. The linear resistive element includes a substrate unit, a function unit and an electrode unit. The substrate unit includes a substrate layer, which is configured to connect the function unit and the electrode unit. The electrode unit includes a first electrode and a second electrode. The first and second electrodes are deposited on the substrate layer, and the function unit is connected between the first and second electrodes. The function unit includes first dielectric layers and resistive layers. The first dielectric layers and the resistive layers are deposited on the substrate layer in an alternately stacked manner. A number of the resistive layers is at least two, and a conductive filament for conductively connecting the first and second electrodes is formed in each of the resistive layers.

